



The way forward

- ★ **Make DR technologies significantly less expensive and thus more appealing to customers (integrated/seamless)**
- ★ **Accelerate innovations in the electricity sector by integrating technologies into “packages” that don’t exist in marketplace**
- ★ **Package technology in forms/footprints that meet energy/DR requirements**

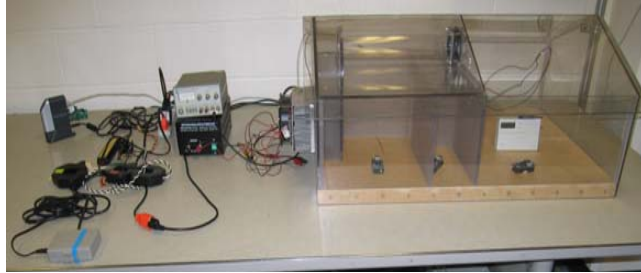


Earlier successes

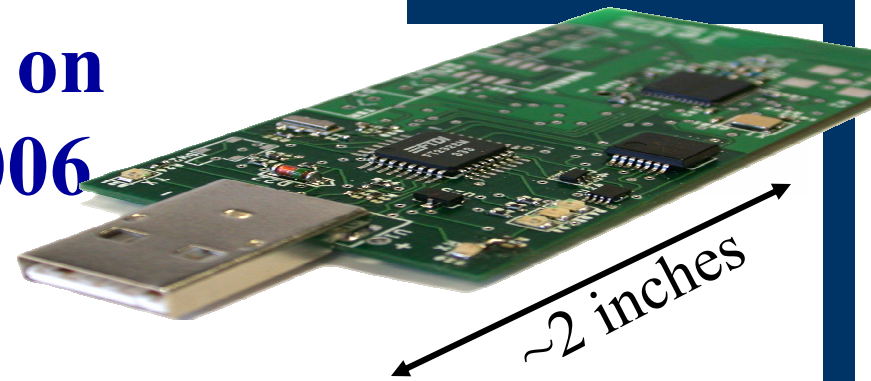
- ★ So far, the DR-ETD project has proven that microcomputers, cheaper radios, TinyOS, MEMS sensors, energy scavenging and WSNs are the enabling technology for a DR responsive system
- ★ Enabling technology for
 - ◆ New Meter
 - ◆ New Thermostat
 - ◆ New TempNode
 - Example of TempNode from 2004/5 publications



DR Applications running on “motes” made in 2003-2006



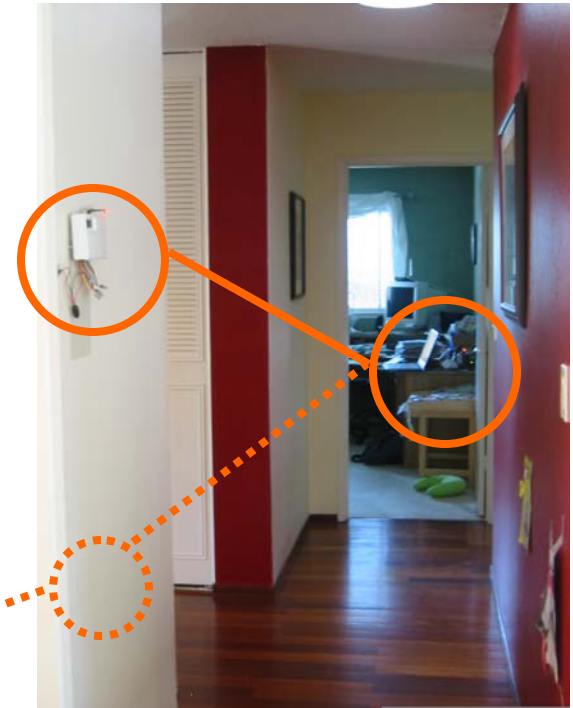
2003



2004/5



2006



*2006 field deployments of REM multi-agent system
with sense and actuation utilizing multi-hop wsn.*



The way forward: Micro-integration

by the millions = “super cheap”

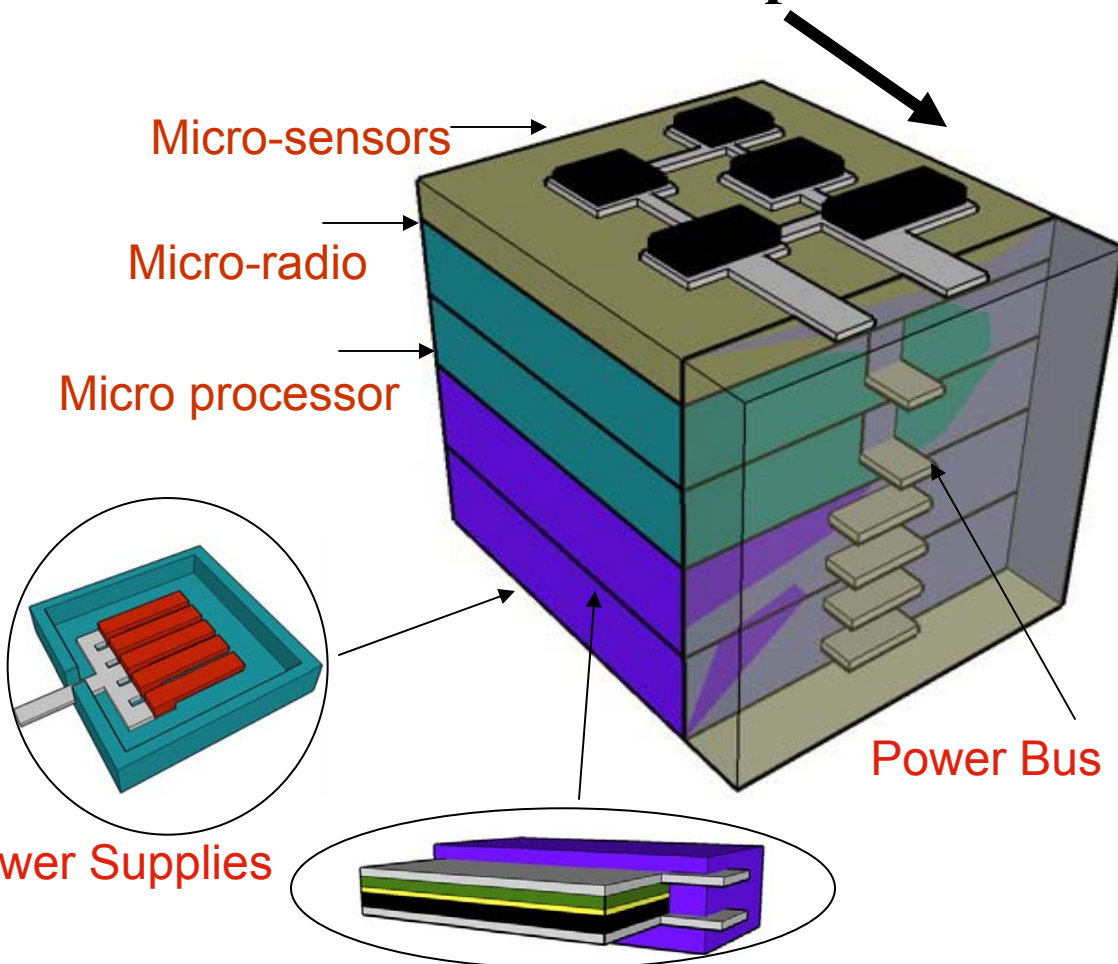
Software applications run on the Hardware platforms

Control logic

Learning algorithms

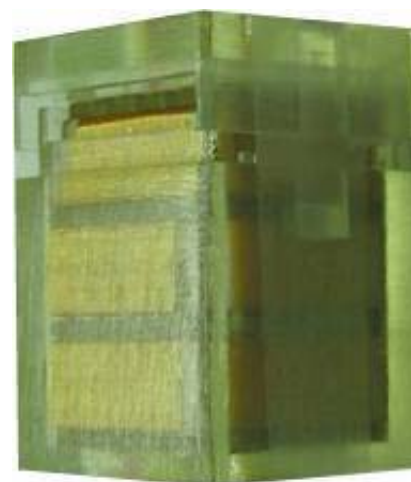
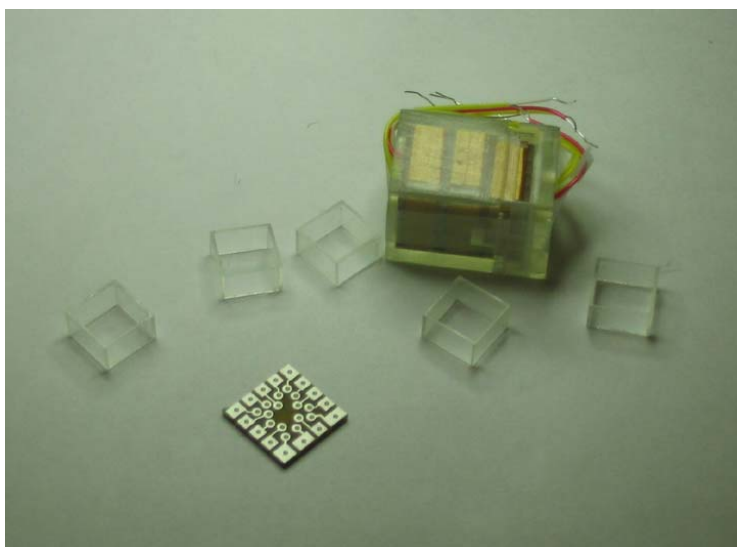
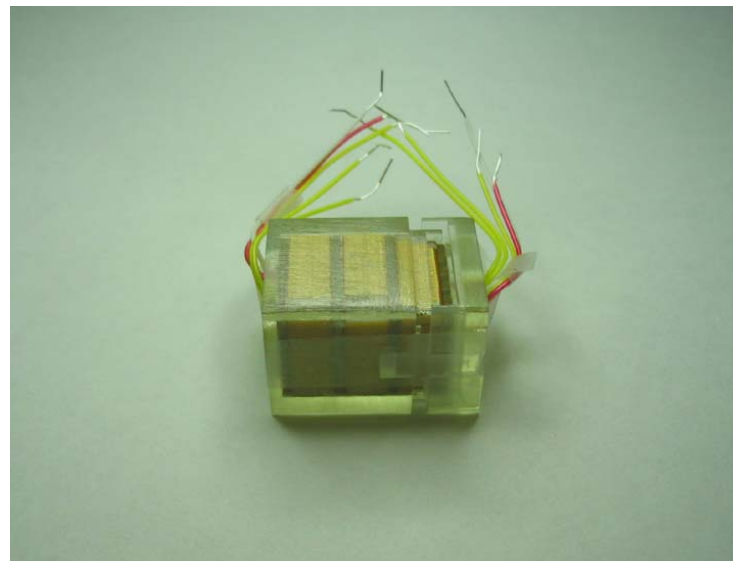
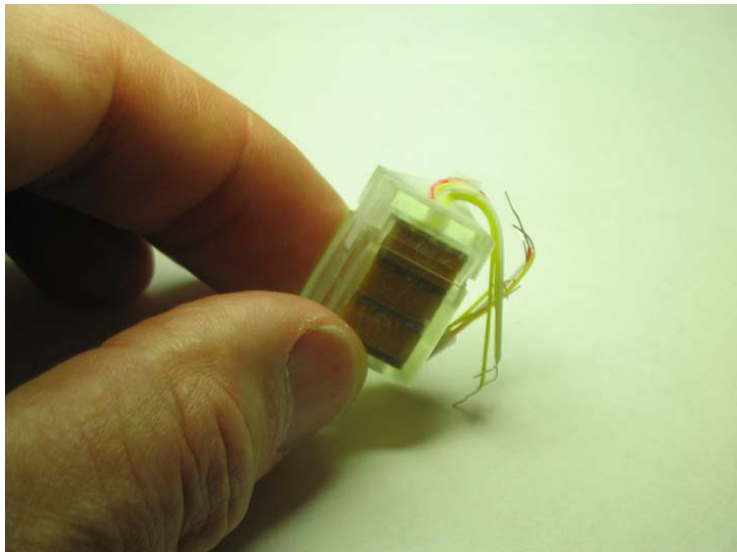
Automation

**Distributed throughout
all computers in the
system**



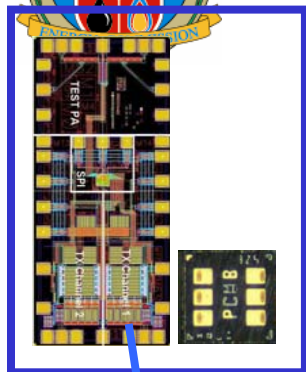


Beginning Micro-integration: PicoCube January 2007

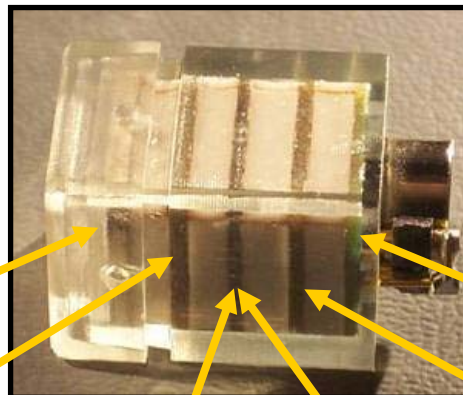




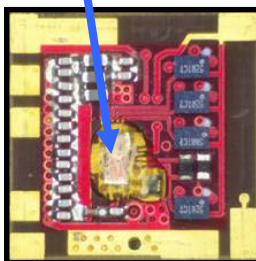
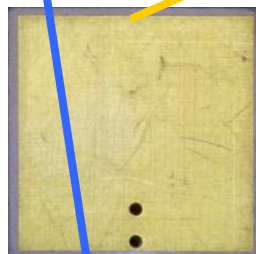
Micro-integration



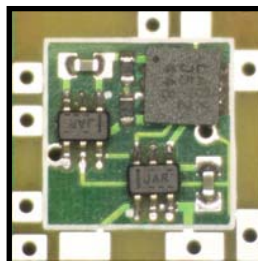
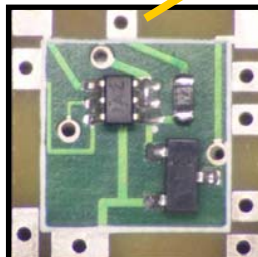
radio
COB
die



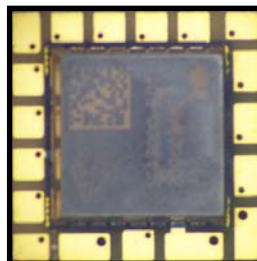
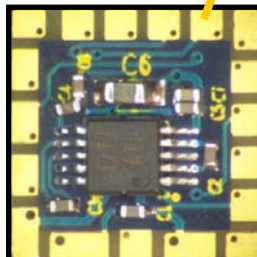
- * Stacked PCBs
- * 1cm square



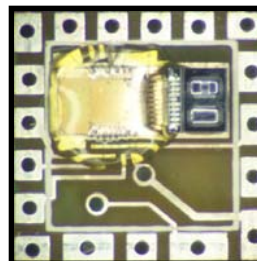
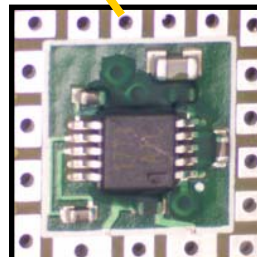
radio board
top/bottom



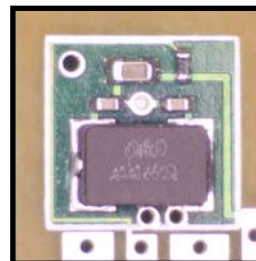
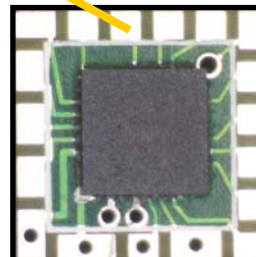
switch/power board
top/bottom



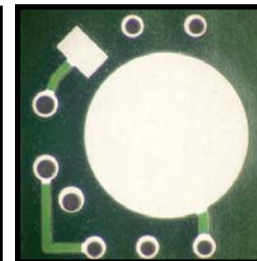
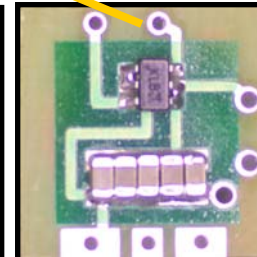
sensor board #2
top/bottom



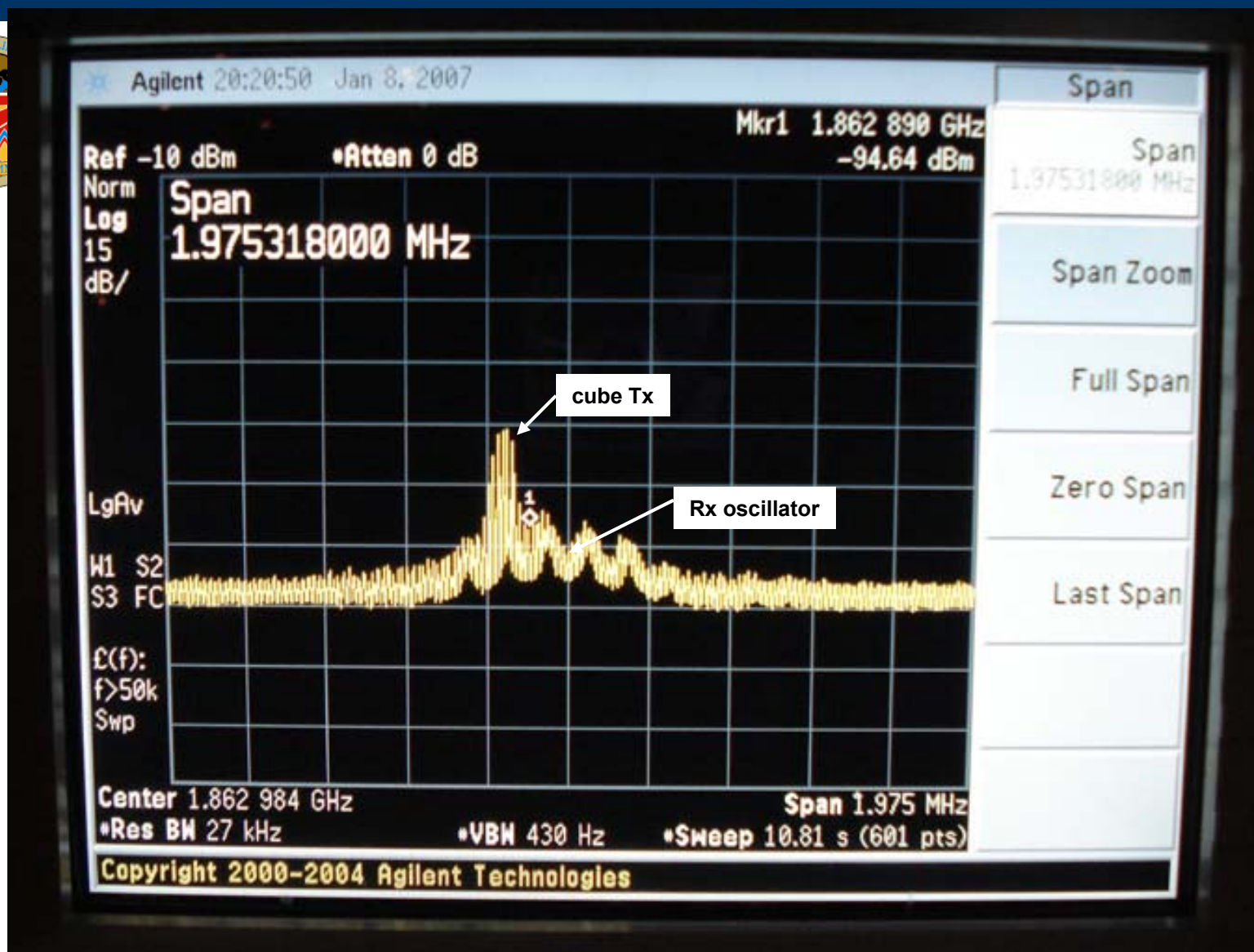
sensor board #1
top/bottom



uC board
top/bottom



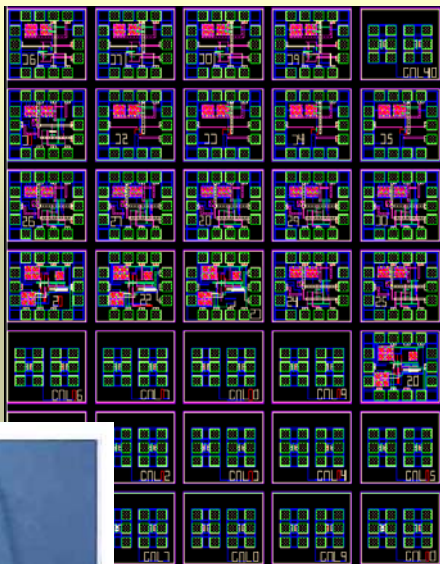
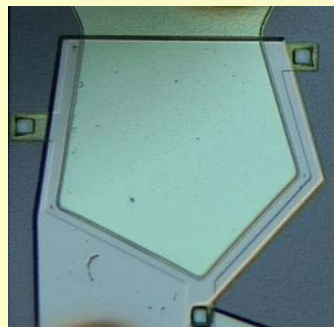
storage board
top/blank bottom



A spectrum analyzer snapshot showing the cube transmitter signal on top of the Rx oscillator signal.

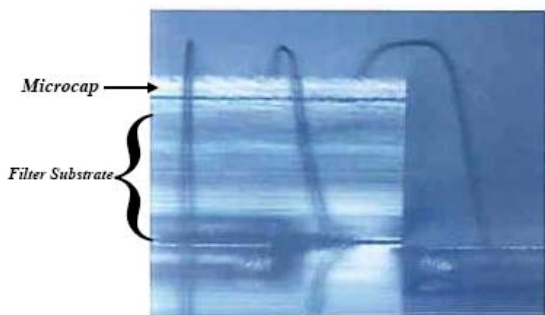


Further Minimization/Packaging



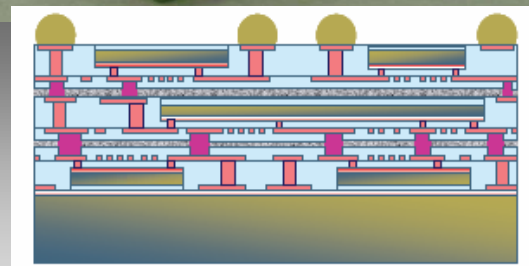
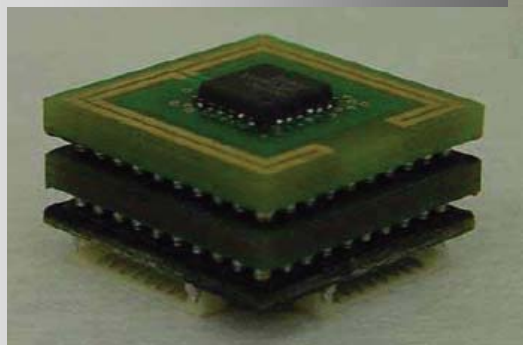
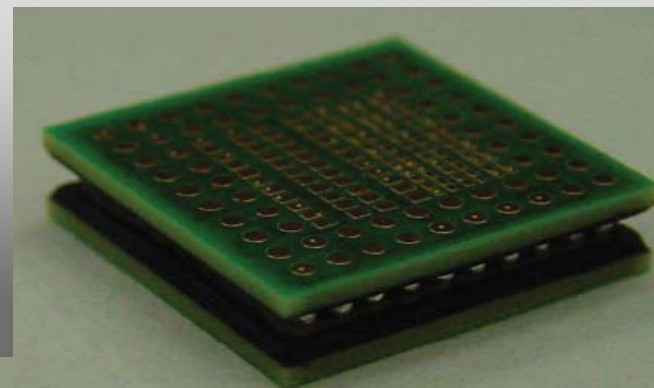
Micro-encapsulation allows co-design/packaging of FBAR resonators and CMOS circuitry

Exploring joint project with IMEC on 3D integration



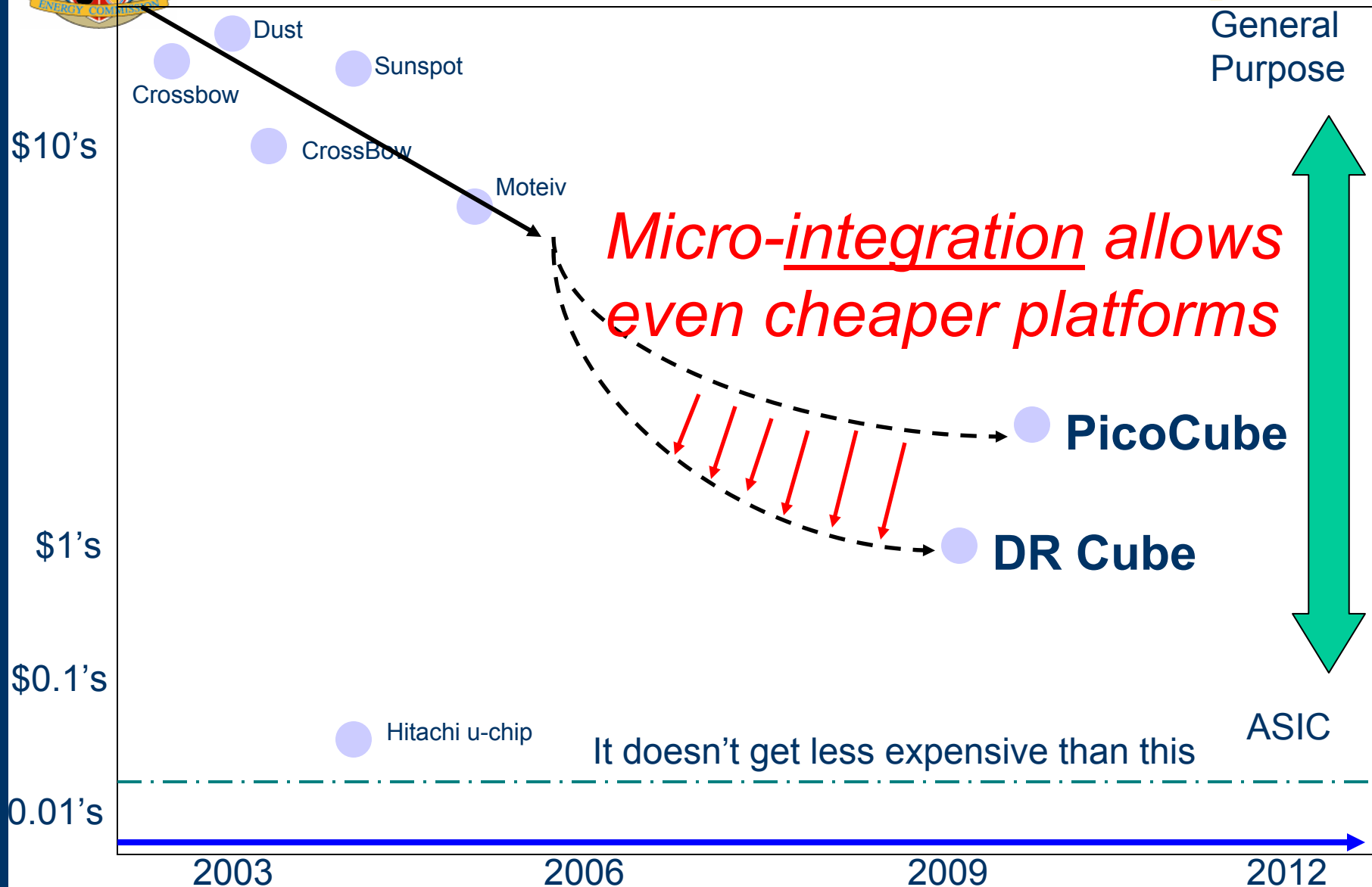
Joint project with Avago and UW

J. Richmond,
M. Mark, N. Pletcher





Pico Cube 2006 >> DR cube 2009



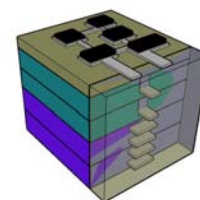
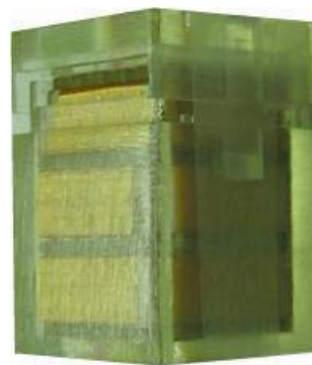


Summary: Micro-integration of Hardware, Software, & Applications

- ★ **10x cost reduction, 10x capability increase**

- ★ **Macro to micro UCB research**

- ◆ Micro-computers
- ◆ Micro-radios
- ◆ Micro-sensors
- ◆ Micro-power supplies
- ◆ DR software applications
- ◆ <\$2 BOM per platform



2007 > 2009

- ★ **Micro-integrated platform for meters, thermostats, temperature-nodes. Enables control and learning.**



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